

#### SURFACE MOUNT SWITCHING DIODE

#### **Features**

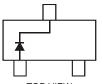
- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- High Conductance
- Lead Free/RoHS Compliant (Note 3)
- "Green" Device (Notes 4 and 5)

#### **Mechanical Data**

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagram
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.006 grams (approximate)



TOP VIEW



TOP VIEW Internal Schematic

## **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		$V_{RM}$	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> VR	80	V
RMS Reverse Voltage		V <sub>R(RMS)</sub>	57	V
Forward Continuous Current (Note 1)		I <sub>FM</sub>	500	mA
Average Rectified Output Current (Note 1)		lo	250	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0μs @ t = 1.0s	I <sub>FSM</sub>	4.0 2.0	А

SOT-323

### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P <sub>D</sub>	200	mW
Thermal Resistance Junction to Ambient Air (Note 1)	$R_{ heta JA}$	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

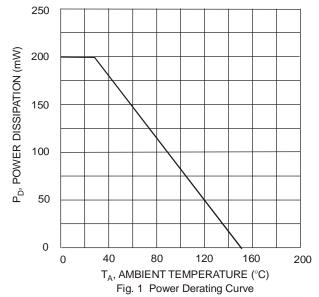
### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

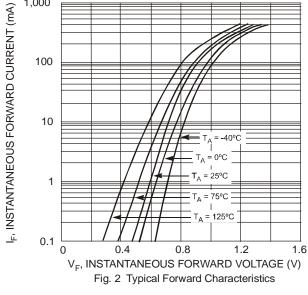
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	80	_	V	$I_R = 2.5 \mu A$
		0.62	0.72		$I_F = 5.0 \text{mA}$
Forward Voltage	VF	_	0.855	V	$I_F = 10mA$
Forward voilage	VF		1.0		$I_F = 100 \text{mA}$
		_	1.25		I <sub>F</sub> = 150mA
			100	nA	$V_R = 70V$
Peak Reverse Current (Note 2)			50	μΑ	$V_R = 75V, T_J = 150^{\circ}C$
reak Reverse Gurrent (Note 2)	I <sub>R</sub>		30	μΑ	V <sub>R</sub> = 25V, T <sub>J</sub> = 150°C
			25	nA	$V_R = 20V$
Total Capacitance	Ст	_	3.5	pF	$V_R = 6V, f = 1.0MHz$
Reverse Recovery Time	t <sub>rr</sub>	_	4.0	ns	$V_R = 6V$ , $I_F = 5mA$

Notes:

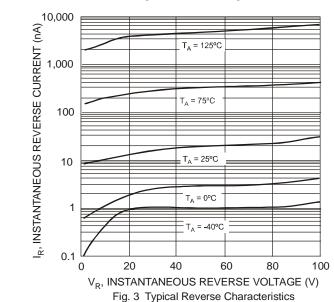
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 2. Short duration pulse test used to minimize self-heating effect.
- No purposefully added lead.
- 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.
- 5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

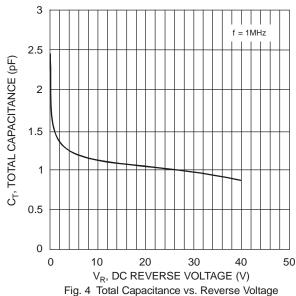






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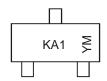


# Ordering Information (Notes 5 & 6)

Part Number	Case	Packaging		
MMBD4448HW-7-F	SOT-323	3000/Tape & Reel		

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



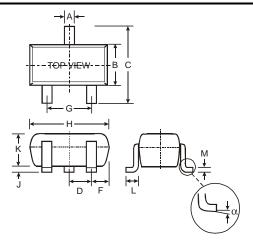
KA1= Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002 M = Month ex: 9 = September

Date Code Key

Year	2000	2001	2002	2003	2004	2005	2006	6 200	7 2008	3 2009	2010	2011	2012
Code	L	М	N	Р	R	S	Т	U	V	W	X	Υ	Z
Month	Jan	Feb	Mar	Apr	Ма	y J	un	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5		6	7	8	9	0	N	D

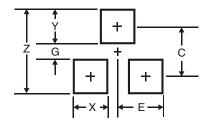


## **Package Outline Dimensions**



SOT-323					
Dim	Min	Max			
Α	0.25	0.40			
В	1.15	1.35			
С	2.00	2.20			
D	0.65 Nominal				
F	0.30 0.40				
G	1.20	1.40			
Н	1.80	2.20			
J	0.0 0.10				
K	0.90 1.00				
L	0.25 0.40				
М	0.10	0.18			
α	0°	8°			
All Dimensions in mm					

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.8
G	1.0
Х	0.7
Υ	0.9
С	1.9
E	0.65

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